

54F38,74F38

54F38 74F38 Quad Two-Input NAND Buffer (Open Collector)



Literature Number: SNOS194A

54F/74F38 Quad Two-Input NAND Buffer (Open Collector)

General Description

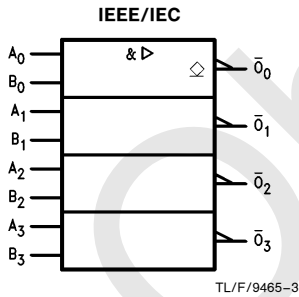
This device contains four independent gates, each of which performs the logic NAND function. The open-collector outputs require external pull-up resistors for proper logical operation.

Commercial	Military	Package Number	Package Description
74F38PC		N14E	14-Lead (0.300" Wide) Molded Dual-In-Line
	54F38DM (Note 2)	J14A	14-Lead Ceramic Dual-In-Line
74F38SC (Note 1)		M14A	14-Lead (0.150" Wide) Molded Small Outline, JEDEC
74F38SJ (Note 1)		M14D	14-Lead (0.300" Wide) Molded Small Outline, EIAJ
	54F38FM (Note 2)	W14B	14-Lead Cerpack
	54F38LM (Note 2)	E20A	20-Lead Ceramic Leadless Chip Carrier, Type C

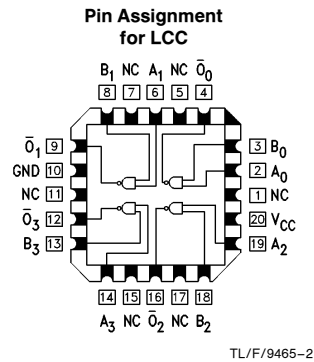
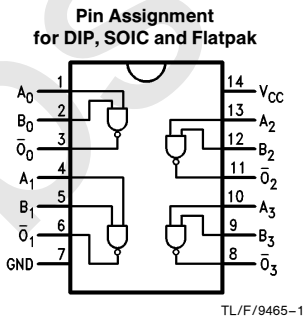
Note 1: Devices also available in 13" reel. Use suffix = SCX and SJX.

Note 2: Military grade device with environmental and burn-in processing. Use suffix = DMQB, FMQB and LMQB.

Logic Symbol



Connection Diagrams



Unit Loading/Fan Out

Pin Names	Description	54F/74F	
		U.L. HIGH/LOW	Input I_{IH}/I_{IL} Output I_{OH}/I_{OL}
A_n, B_n $\bar{O}_n$	Inputs Outputs	1.0/2.0 OC*/106.6 (80)	20 μ A/ -1.2 mA OC*/64 mA (48 mA)

*OC = Open Collector

Function Table

Inputs		Output
A	B	$\bar{O}$
L	L	H
L	H	H
H	L	H
H	H	L

H = HIGH Voltage Level

L = LOW Voltage Level

Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Storage Temperature	−65°C to +150°C
Ambient Temperature under Bias	−55°C to +125°C
Junction Temperature under Bias	−55°C to +175°C
Plastic	−55°C to +150°C
V _{CC} Pin Potential to Ground Pin	−0.5V to +7.0V
Input Voltage (Note 2)	−0.5V to +7.0V
Input Current (Note 2)	−30 mA to +5.0 mA
Voltage Applied to Output in HIGH State (with V _{CC} = 0V)	
Standard Output	−0.5V to V _{CC}
TRI-STATE® Output	−0.5V to +5.5V

Current Applied to Output in LOW State (Max) twice the rated I_{OL} (mA)

Note 1: Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 2: Either voltage limit or current limit is sufficient to protect inputs.

Recommended Operating Conditions

Free Air Ambient Temperature	
Military	−55°C to +125°C
Commercial	0°C to +70°C
Supply Voltage	
Military	+4.5V to +5.5V
Commercial	+4.5V to +5.5V

DC Electrical Characteristics

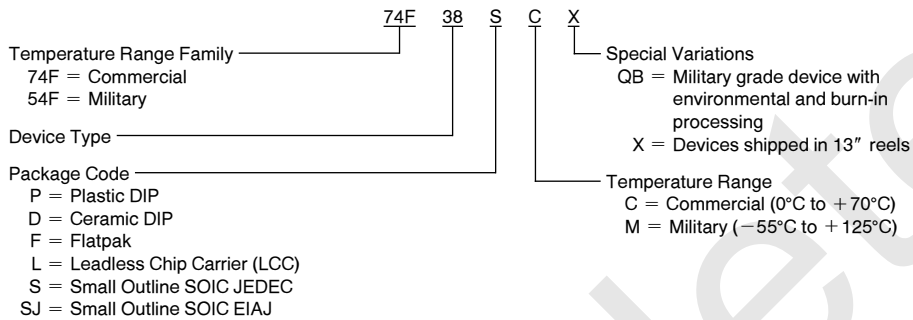
Symbol	Parameter	54F/74F			Units	V _{CC}	Conditions
		Min	Typ	Max			
V _{IH}	Input HIGH Voltage	2.0			V		Recognized as a HIGH Signal
V _{IL}	Input LOW Voltage			0.8	V		Recognized as a LOW Signal
V _{CD}	Input Clamp Diode Voltage			−1.2	V	Min	I _{IN} = −18 mA
V _{OL}	Output LOW Voltage	54F 10% V _{CC} 74F 10% V _{CC}		0.55 0.55	V	Min	I _{OL} = 48 mA I _{OL} = 64 mA
I _{IH}	Input HIGH Current	54F 74F		20.0 5.0	μA	Max	V _{IN} = 2.7V
I _{BVI}	Input HIGH Current Breakdown Test	54F 74F		100 7.0	μA	Max	V _{IN} = 7.0V
V _{ID}	Input Leakage Test	74F	4.75		V	0.0	I _{ID} = 1.9 μA All Other Pins Grounded
I _{OD}	Output Leakage Circuit Current	74F		3.75	μA	0.0	V _{IOD} = 150 mV All Other Pins Grounded
I _{IL}	Input LOW Current			−1.2	mA	Max	V _{IN} = 0.5V
I _{OHC}	Open Collector, Output OFF Leakage Test			250	μA	Min	V _{OUT} = V _{CC}
I _{CCH}	Power Supply Current		2.1	7.0	mA	Max	V _O = HIGH
I _{CCL}	Power Supply Current		26.0	30.0	mA	Max	V _O = LOW

AC Electrical Characteristics

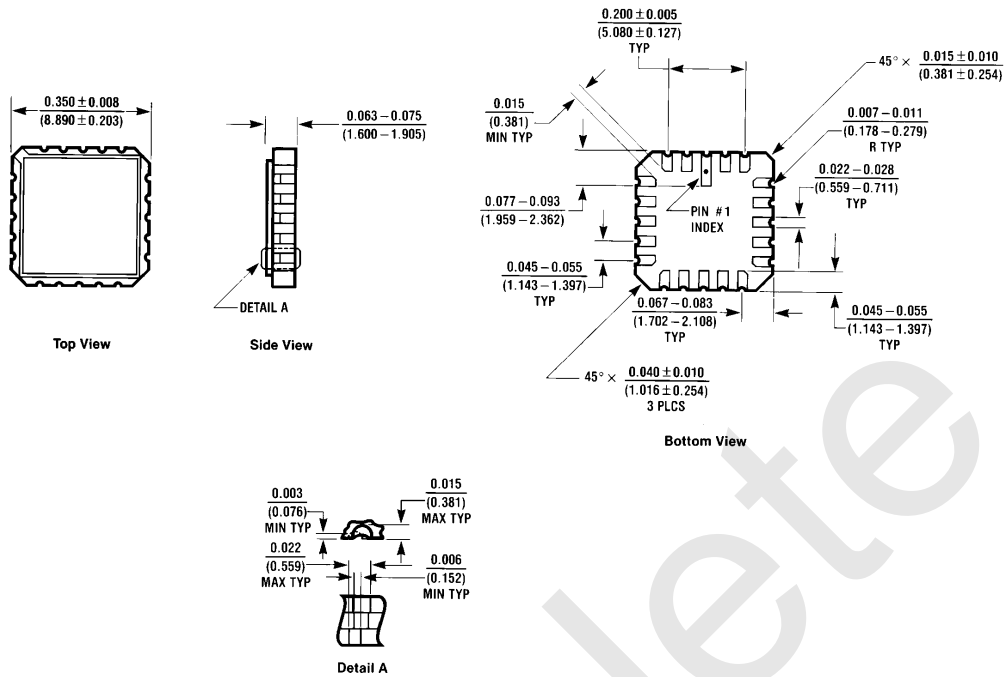
Symbol	Parameter	74F			54F		74F		Units
		T _A = +25°C V _{CC} = +5.0V C _L = 50 pF			T _A , V _{CC} = Mil C _L = 50 pF		T _A , V _{CC} = Com C _L = 50 pF		
		Min	Typ	Max	Min	Max	Min	Max	
t _{PLH}	Propagation Delay	6.5	9.7	12.5	6.5	14.5	6.5	13.0	ns
t _{PHL}	A _n , B _n to $\overline{O}_n$	1.5	2.1	5.0	1.0	5.5	1.5	5.5	

Ordering Information

The device number is used to form part of a simplified purchasing code where the package type and temperature range are defined as follows:



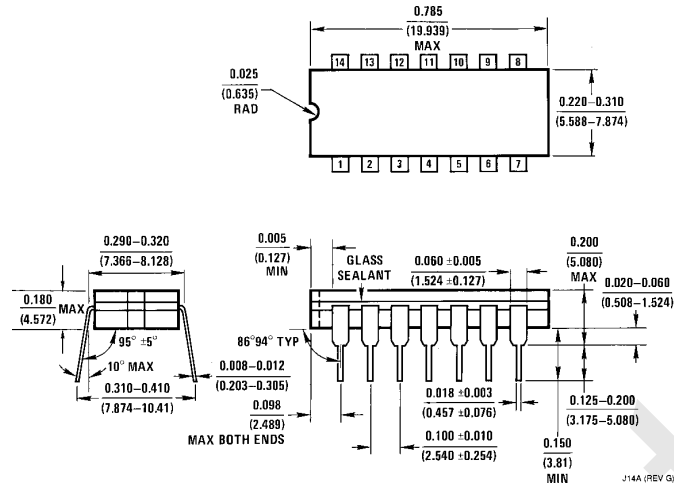
Physical Dimensions inches (millimeters)



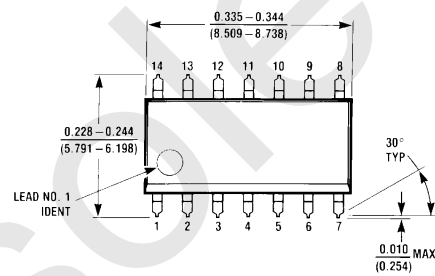
**20-Lead Ceramic Leadless Chip Carrier (L)
NS Package Number E20A**

E20A (REV D)

Physical Dimensions inches (millimeters) (Continued)

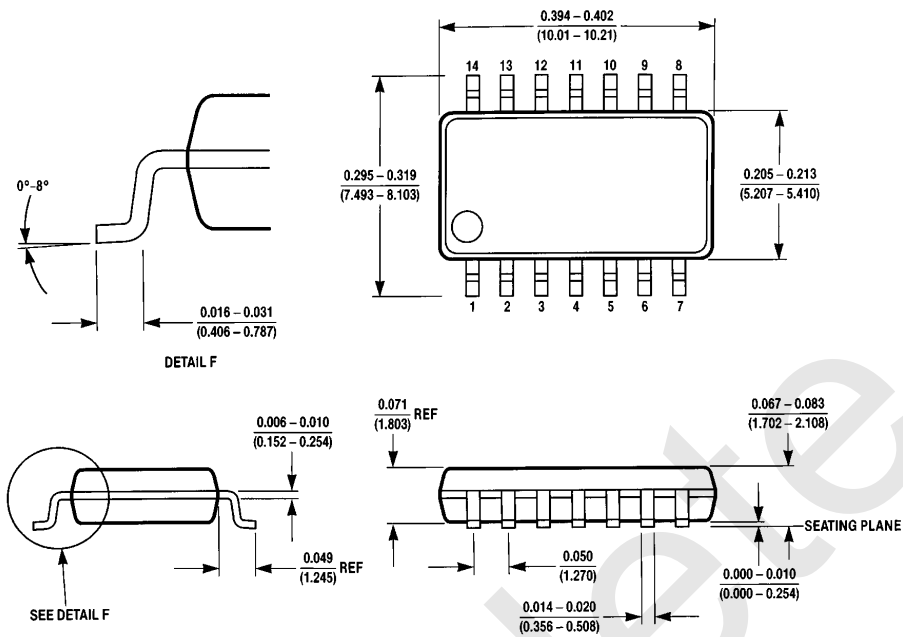


14-Lead Ceramic Dual-In-Line Package (D)
NS Package Number J14A



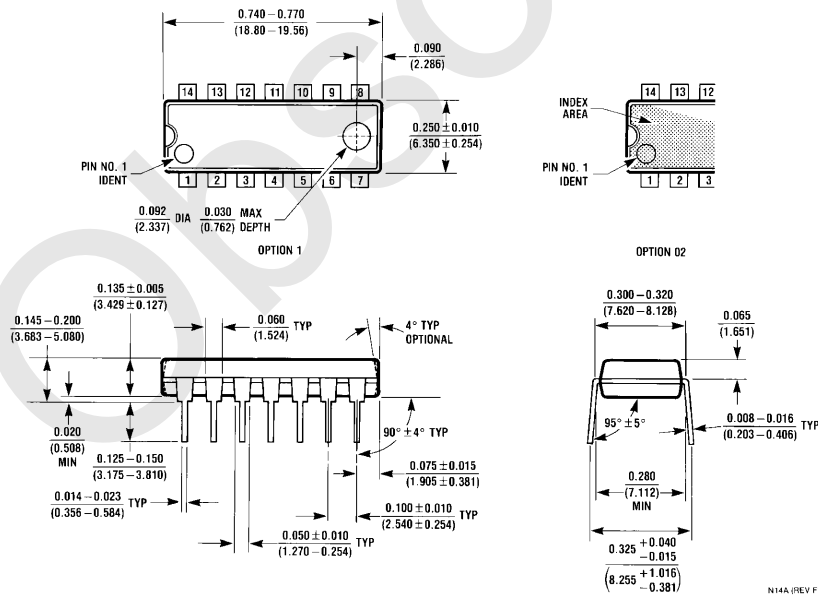
14-Lead (0.150" Wide) Molded Small Outline Package, JEDEC (S)
NS Package Number M14A

Physical Dimensions inches (millimeters) (Continued)



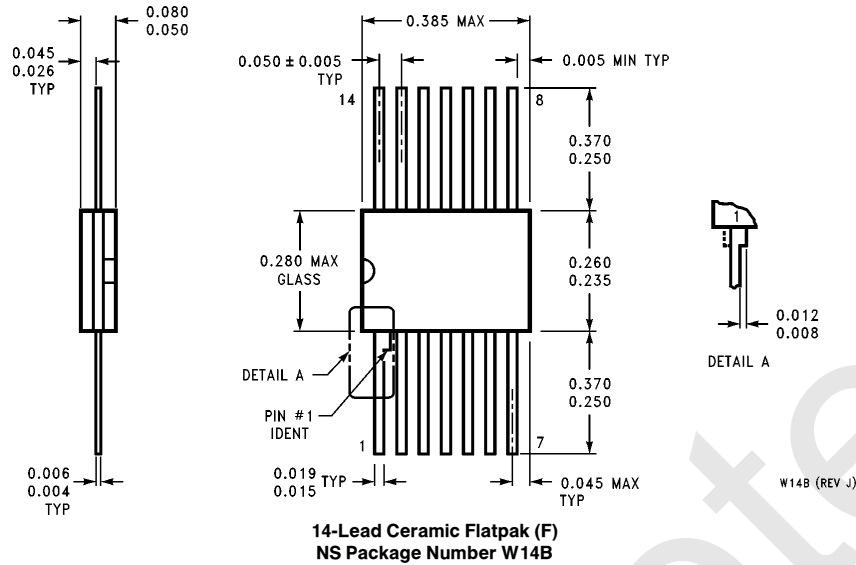
M14D (REV A)

14-Lead (0.300" Wide) Molded Small Outline Package, EIAJ (SJ)
NS Package Number M14D



N14A (REV F)

14-Lead (0.300" Wide) Molded Dual-In-Line Package (P)
NS Package Number N14A

Physical Dimensions inches (millimeters) (Continued)**LIFE SUPPORT POLICY**

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